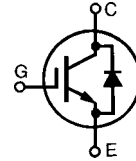


High Voltage IGBT with Diode

IXSK35N120AU1

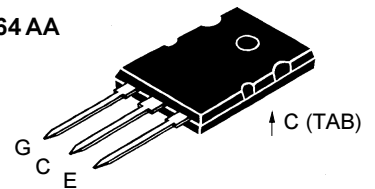
Combi Pack
Short Circuit SOA Capability

$$\begin{aligned} V_{CES} &= 1200 \text{ V} \\ I_{C25} &= 70 \text{ A} \\ V_{CE(sat)} &= 4 \text{ V} \end{aligned}$$



Symbol	Test Conditions	Maximum Ratings	
V_{CES}	$T_J = 25^\circ\text{C}$ to 150°C	1200	V
V_{CGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GE} = 1 \text{ M}\Omega$	1200	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	$T_C = 25^\circ\text{C}$	70	A
I_{C90}	$T_C = 90^\circ\text{C}$	35	A
I_{CM}	$T_C = 25^\circ\text{C}$, 1 ms	140	A
SSOA (RBSOA)	$V_{GE} = 15 \text{ V}$, $T_J = 125^\circ\text{C}$, $R_G = 22 \Omega$ Clamped inductive load, $L = 30 \mu\text{H}$	$I_{CM} = 70$ @ $0.8 V_{CES}$	A
t_{SC} (SCSOA)	$V_{GE} = 15 \text{ V}$, $V_{CE} = 720 \text{ V}$, $T_J = 125^\circ\text{C}$ $R_G = 22 \Omega$, non repetitive	10	μs
P_C	$T_C = 25^\circ\text{C}$	IGBT	300 W
		Diode	190 W
T_J		-55 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		-55 ... +150	$^\circ\text{C}$
T_L	1.6 mm (0.063 in) from case for 10 s	300	$^\circ\text{C}$
M_d	Mounting torque	1.15/13	Nm/lb.in.
Weight		10	g

TO-264 AA



G = Gate,
E = Emitter,
C = Collector,
TAB = Collector

Features

- International standard package JEDEC TO-264 AA
- High frequency IGBT and anti-parallel FRED in one package
- 2nd generation HDMOS™ process
- Low $V_{CE(sat)}$ - for minimum on-state conduction losses
- MOS Gate turn-on - drive simplicity
- Fast Recovery Epitaxial Diode (FRED) - soft recovery with low I_{RM}

Applications

- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

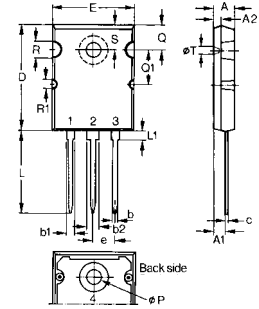
Advantages

- Space savings (two devices in one package)
- Easy to mount with one screw (isolated mounting screw hole)
- High power density

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
BV_{CES}	$I_C = 5 \text{ mA}$, $V_{GE} = 0 \text{ V}$	1200		V
$V_{GE(th)}$	$I_C = 4 \text{ mA}$, $V_{CE} = V_{GE}$	4		V
I_{CES} ①	$V_{CE} = 0.8 \cdot V_{CES}$ $V_{GE} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$		750 μA
		$T_J = 125^\circ\text{C}$		15 mA
I_{GES}	$V_{CE} = 0 \text{ V}$, $V_{GE} = \pm 20 \text{ V}$			$\pm 100 \text{ nA}$
$V_{CE(sat)}$	$I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$			4 V

① Device must be heatsunk for high temperature measurements to avoid thermal runaway. IXYS reserves the right to change limits, test conditions and dimensions.

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)			
		min.	typ.	max.	
g_{fs}	$I_C = I_{C90}; V_{CE} = 10\text{ V}$, Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$	20	26	S	
$I_{C(on)}$	$V_{GE} = 15\text{ V}, V_{CE} = 10\text{ V}$		170	A	
C_{ies} C_{oes} C_{res}	} $V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$		3900	pF	
			295	pF	
			60	pF	
Q_g Q_{ge} Q_{gc}	} $I_C = I_{C90}, V_{GE} = 15\text{ V}, V_{CE} = 0.5 V_{CES}$		150	nC	
			40	60	nC
			70	100	nC
$t_{d(on)}$ t_{ri} $t_{d(off)}$ t_{fi} E_{off}	} Inductive load, $T_J = 25^\circ\text{C}$ $I_C = I_{C90}, V_{GE} = 15\text{ V}, L = 100\ \mu\text{H}$ $R_G = 2.7\ \Omega, V_{CE} = 0.8 V_{CES}$ Switching times may increase for V_{CE} (Clamp) $> 0.8 V_{CES}$, higher T_J or increased R_G .		80	ns	
			150	ns	
			400	900	ns
			500	700	ns
			10		mJ
$t_{d(on)}$ t_{ri} E_{on} $t_{d(off)}$ t_{fi} E_{off}	} Inductive load, $T_J = 125^\circ\text{C}$ $I_C = I_{C90}, V_{GE} = 15\text{ V}, L = 100\ \mu\text{H}$ $R_G = 2.7\ \Omega, V_{CE} = 0.8 V_{CES}$ Switching times may increase for V_{CE} (Clamp) $> 0.8 V_{CES}$, higher T_J or increased R_G .		80	ns	
			150	ns	
			8		mJ
			400	ns	
			700	ns	
			15		mJ
R_{thJC} R_{thCK}				0.42 KW	
		0.15		KW	

TO-264 AA Outline


Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.82	5.13	.190	.202
A1	2.54	2.89	.100	.114
A2	2.00	2.10	.079	.083
b	1.12	1.42	.044	.056
b1	2.39	2.69	.094	.106
b2	2.90	3.09	.114	.122
c	0.53	0.83	.021	.033
D	25.91	26.16	1.020	1.030
E	19.81	19.96	.780	.786
e	5.46BSC		.215BSC	
J	0.00	0.25	.000	.010
K	0.00	0.25	.000	.010
L	20.32	20.83	.800	.820
L1	2.29	2.59	.090	.102
P	3.17	3.66	.125	.144
Q	6.07	6.27	.239	.247
Q1	8.38	8.69	.330	.342
R	3.81	4.32	.150	.170
R1	1.78	2.29	.070	.090
S	6.04	6.30	.238	.248
T	1.57	1.83	.062	.072

Reverse Diode (FRED)

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
V_F	$I_F = I_{C90}, V_{GE} = 0\text{ V}$, Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $d \leq 2\%$, $T_J = 125^\circ\text{C}$			2.35 V
I_{RM} t_{rr}	} $I_F = I_{C90}, V_{GE} = 0\text{ V}, -di_F/dt = 480\text{ A}/\mu\text{s}$ $V_R = 540\text{ V}$ $T_J = 100^\circ\text{C}$ $I_F = 1\text{ A}; -di_F/dt = 200\text{ A}/\mu\text{s}; V_R = 30\text{ V}$ $T_J = 25^\circ\text{C}$		32	36 A
			225	ns
			40	60 ns
R_{thJC}				0.65 KW

IXSK 35N120AU1 characteristic curves are located in the IXSX 35N120AU1.

IXYS reserves the right to change limits, test conditions, and dimensions.

 IXYS MOSFETS and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715
 4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025

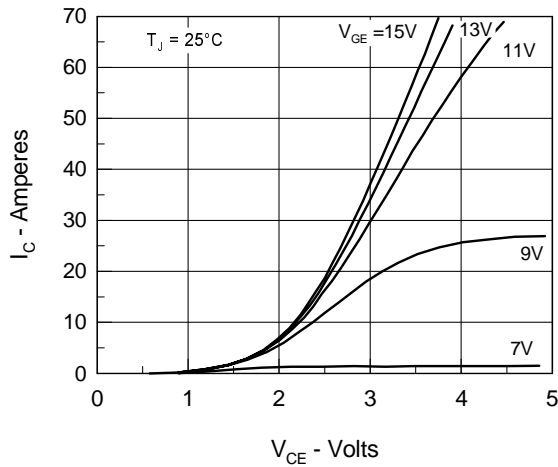
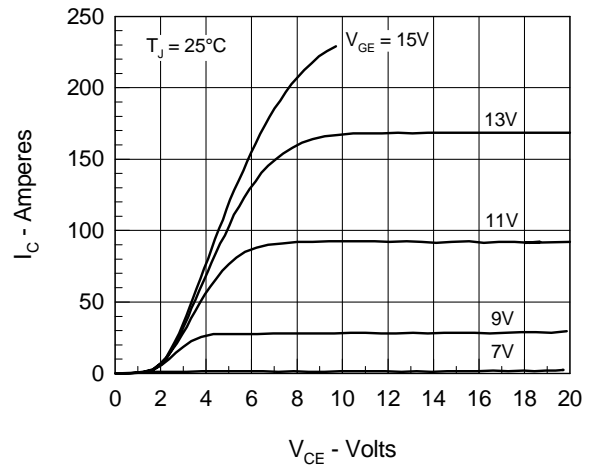
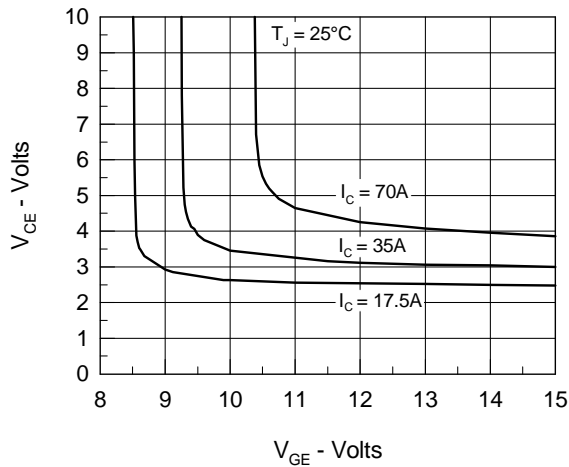
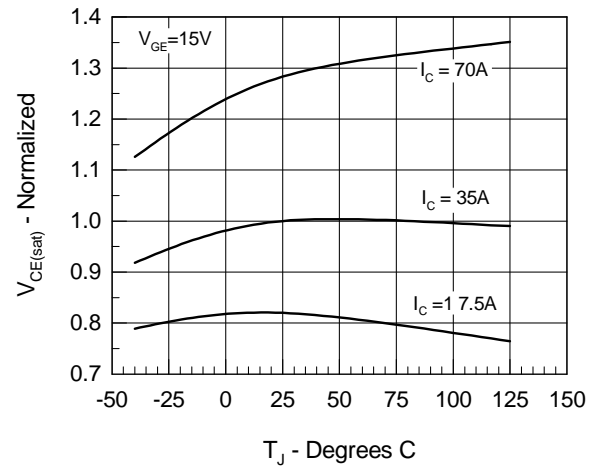
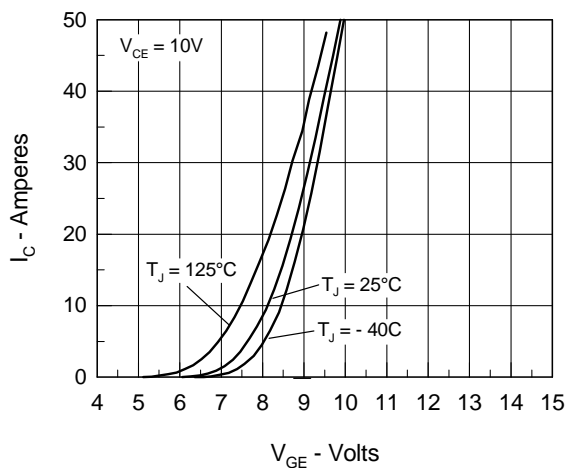
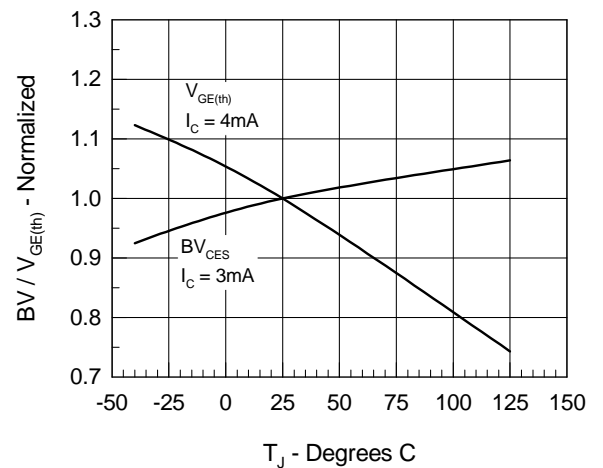
Fig.1 Saturation Characteristics

Fig.2 Output Characteristics

Fig.3 Collector-Emitter Voltage vs. Gate-Emitter Voltage

Fig.4 Temperature Dependence of Output Saturation Voltage

Fig.5 Input Admittance

Fig.6 Temperature Dependence of Breakdown and Threshold Voltage


Fig.7 Turn-Off Energy per Pulse and Fall Time on Collector Current

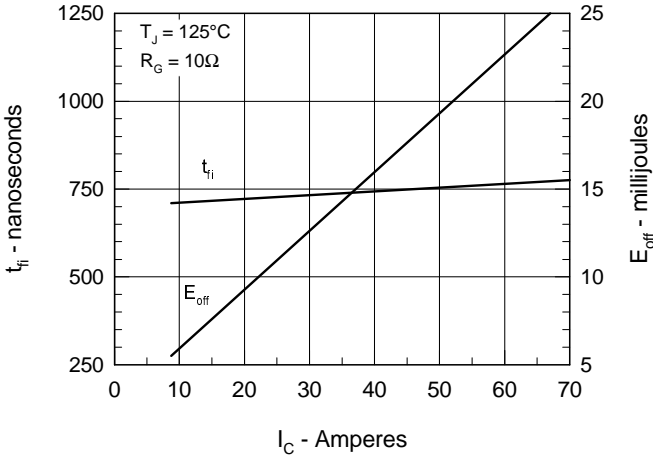


Fig.8 Dependence of Turn-Off Energy Per Pulse and Fall Time on R_G

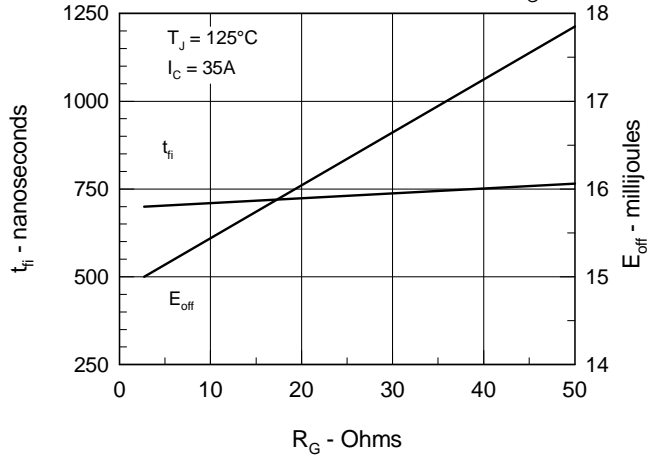


Fig.9 Gate Charge Characteristic Curve

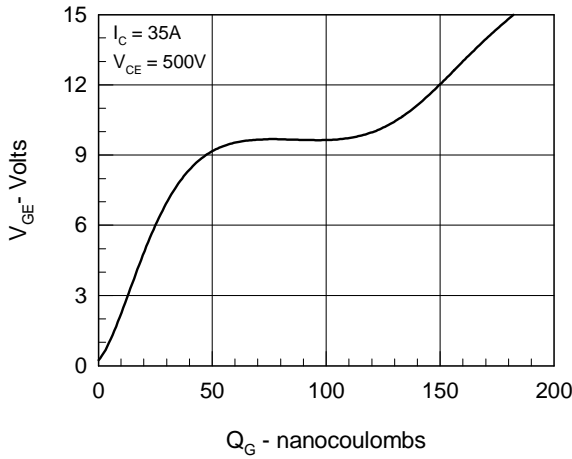


Fig.10 Turn-Off Safe Operating Area

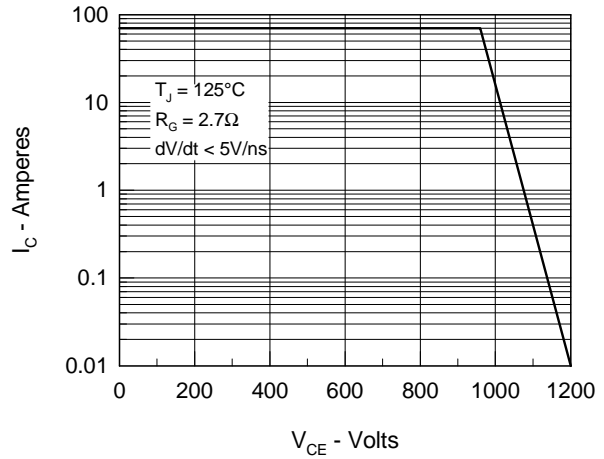
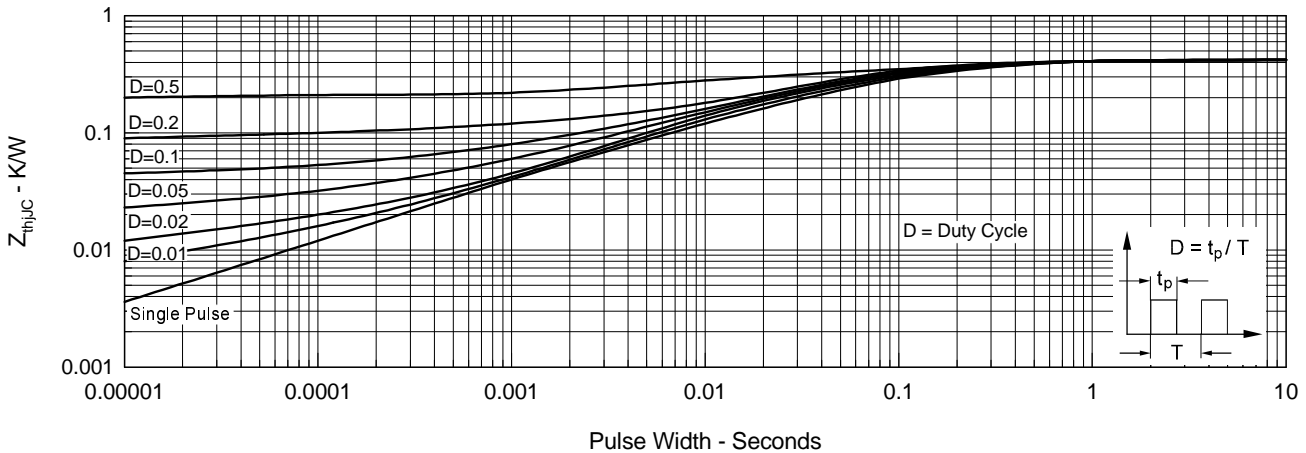


Fig.11 Transient Thermal Impedance



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4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025

Fig. 12 Maximum Forward Voltage Drop

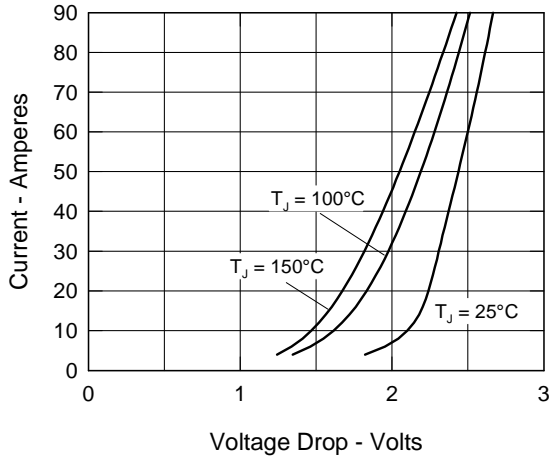


Fig. 13 Peak Forward Voltage V_{FR} and Forward Recovery Time t_{FR}

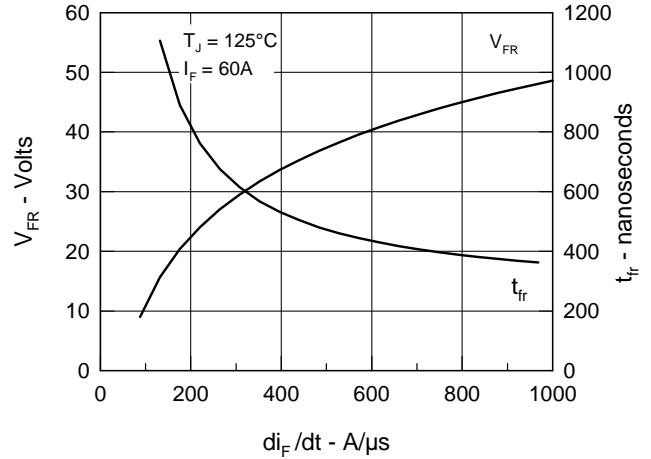


Fig. 14 Junction Temperature Dependence of I_{RM} and Q_r

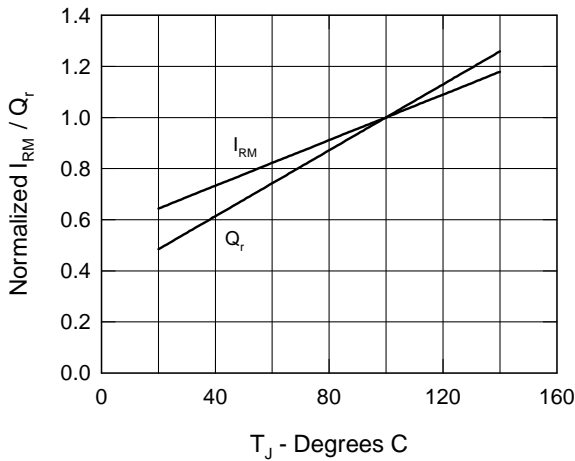


Fig. 15 Reverse Recovery Charge

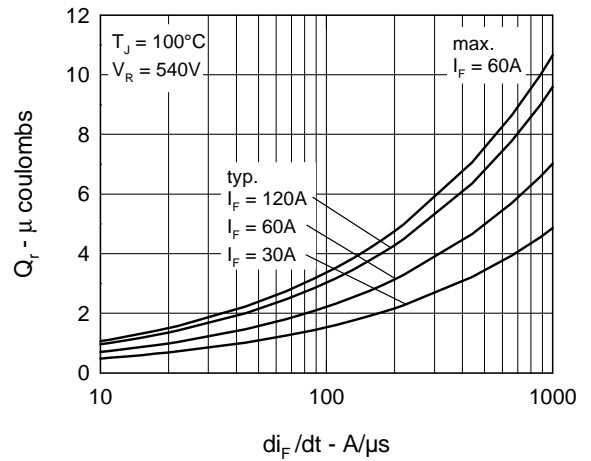


Fig. 16 Peak Reverse Recovery Current

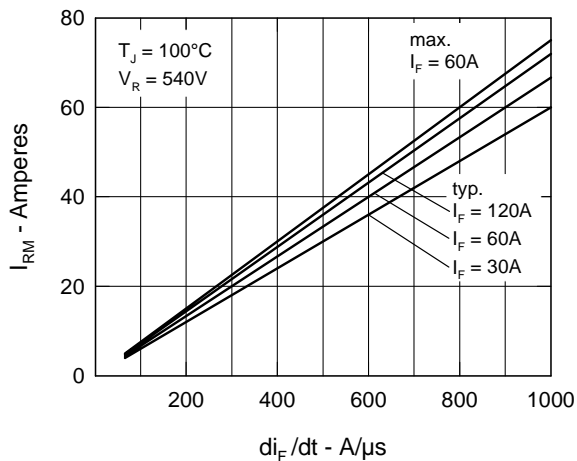


Fig. 17 Reverse Recovery Time

